

850V Depletion-Mode Power MOSFET

General Features

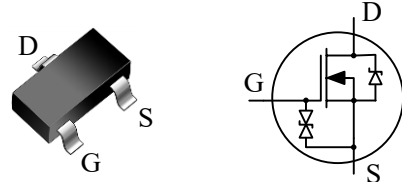
- Depletion Mode (Normally On)
- ESD Improved Capability
- Fast Switching Speed
- RoHS Compliant
- Halogen-free Available

BV_{DSX}	$R_{DS(ON)(TYP.)}$	I_{DSS}
850V	200Ω	20mA

SOT-23

Applications

- Normally-On Switches
- Converters
- Protection Circuits
- Telecommunications
- Current Regulators
- Power Supply



Ordering Information

Part Number	Package	Marking	Remark
DMZ85200E	SOT-23	85300	Halogen Free

Absolute Maximum Ratings

$T_A=25^{\circ}\text{C}$ unless otherwise specified

Symbol	Parameter	DMZ85200E	Unit
V_{DSX}	Drain-to-Source Voltage ^[1]	850	V
I_D	Continuous Drain Current	20	mA
I_{DM}	Pulsed Drain Current ^[2]	80	
P_D	Power Dissipation	0.5	W
V_{GS}	Gate-to-Source Voltage	±20	V
T_L	Soldering Temperature Distance of 1.6mm from case for 10 seconds	300	°C
T_J and T_{STG}	Operating and Storage Temperature Range	-55 to 150	

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" may cause permanent damage to the device.

Thermal Characteristics

Symbol	Parameter	DMZ85200E	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	250	K/W

Electrical Characteristics

OFF Characteristics

 $T_A = 25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
BV_{DSX}	Drain-to-Source Breakdown Voltage	850	--	--	V	$V_{GS} = -10\text{V}$, $I_D = 250\mu\text{A}$
$I_{D(OFF)}$	Drain-to-Source Leakage Current	--	--	10	μA	$V_{DS} = 850\text{V}$, $V_{GS} = -10\text{V}$
I_{GSS}	Gate-to-Source Leakage Current	--	--	± 20	μA	$V_{GS} = \pm 20\text{V}$, $V_{DS} = 0\text{V}$

ON Characteristics

 $T_A = 25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
I_{DSS}	Saturated Drain-to-Source Current	20	--	--	mA	$V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$
$R_{DS(ON)}$	Static Drain-to-Source On-Resistance	--	200	300	Ω	$V_{GS} = 0\text{V}$, $I_D = 10\text{mA}$ ^[3]
$V_{GS(OFF)}$	Gate-to-Source Cut off Voltage	-1.5	--	-3.3	V	$V_{DS} = 9\text{V}$, $I_D = 8\mu\text{A}$
gfs	Forward Transconductance	--	--	--	S	$V_{DS} = 20\text{V}$, $I_D = 10\text{mA}$

Dynamic Characteristics

Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
C_{iss}	Input Capacitance	--	--	--	pF	$V_{GS} = -10\text{V}$ $V_{DS} = 50\text{V}$ $f = 1.0\text{MHz}$
C_{oss}	Output Capacitance	--	--	--		
C_{rss}	Reverse Transfer Capacitance	--	--	--		
Q_g	Total Gate Charge	--	--	--	nC	$V_{GS} = -10\text{V} \sim 5\text{V}$ $V_{DS} = 150\text{V}$, $I_D = 10\text{mA}$
Q_{gs}	Gate-to-Source Charge	--	--	--		
Q_{gd}	Gate-to-Drain (Miller) Charge	--	--	--		

Resistive Switching Characteristics

Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$t_{d(on)}$	Turn-on Delay Time	--	--	--	ns	$V_{GS} = -10\text{V} \sim 0\text{V}$ $V_{DD} = 50\text{V}$, $I_D = 10\text{mA}$ $R_G = 10\Omega$
t_{rise}	Rise Time	--	--	--		
$t_{d(off)}$	Turn-off Delay Time	--	--	--		
t_{fall}	Fall Time	--	--	--		



Source-Drain Diode Characteristics

$T_A=25^{\circ}\text{C}$ unless otherwise specified

Symbol	Parameter	Min	Typ.	Max.	Units	Test Conditions
V_{SD}	Diode Forward Voltage	--	--	1.2	V	$I_{SD}=10\text{mA}$, $V_{GS}=-10\text{V}$

NOTE:

[1] $T_J=+25^{\circ}\text{C}$ to $+150^{\circ}\text{C}$

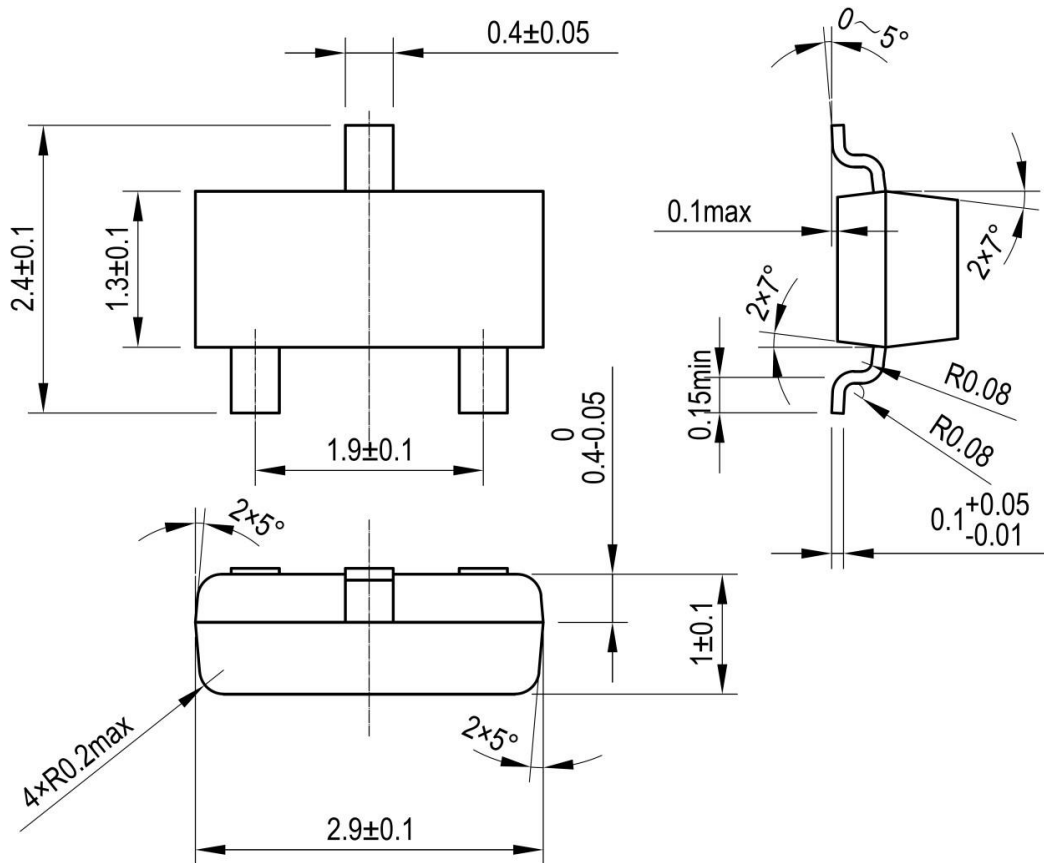
[2] Repetitive rating, pulse width limited by maximum junction temperature.

[3] Pulse width $\leq 380\mu\text{s}$; duty cycle $\leq 2\%$.

Package Dimensions

SOT-23

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